MA3XD15

Silicon epitaxial planar type

For high frequency rectification

■ Features

• Low forward voltage: $V_F < 0.45 \text{ V}$ • Small reverse current: $I_R < 100 \ \mu\text{A}$

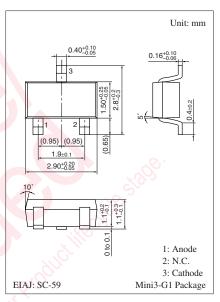
• Forward current (Average) $I_{F(AV)} = 1$ A rectification is possible

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	20	V
Repetitive peak reverse voltage	V _{RRM}	25	V
Non-repetitive peak forward surge current *2	I _{FSM}	3	A
Forward current (Average) *1	$I_{F(AV)}$	1.0	A
Junction temperature	T_{j}	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

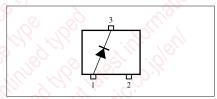
Note) *1: Mounted on an alumina PC board

*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



Marking Symbol: M5N

Internal Connection

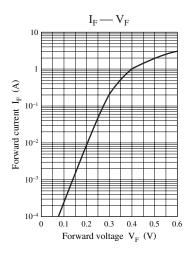


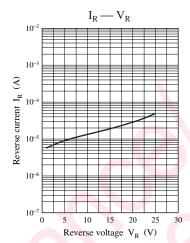
■ Electrical Characteristics T_a = 25°C ± 3°C

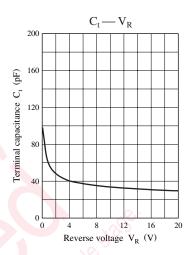
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 1.0 \text{ A}$	150		0.45	V
Reverse current	I_R	V _R = 20 V			100	μΑ
Terminal capacitance	C _t	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$		120		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.







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